

### STATUS OF THE CLAIMS

The status of the claims of the present application stands as follows:

1. **(Canceled).**
2. **(Canceled).**
3. **(Canceled).**
4. **(Currently Amended)** ~~An apparatus~~ A system according to claim 318, wherein said brush roller comprises a polymer filled with an electrically-conductive material.
5. **(Previously Presented)** An apparatus according to claim 4, wherein said brush roller comprises a carbon-filled perfluoroalkoxyalkane.
6. **(Canceled)**
7. **(Currently Amended)** ~~An apparatus~~ A system according to claim 318, wherein said brush roller comprises a foam rubber cleaning portion.
8. **(Canceled)**
9. **(Canceled)**
10. **(Previously Presented)** A method of removing surface contaminants from a surface of a microelectronics wafer that may have a static electrical charge thereon, comprising the steps of:
  - (a) providing a microelectronics wafer having a surface; and
  - (b) cleaning said surface of said microelectronics wafer with a conductive rotating wafer-cleaning member so as to remove at least some of the surface contaminants, and so as to simultaneously create an electrical ground path between said surface and an electrical ground through said conductive rotating wafer-cleaning member.
11. **(Canceled)**
12. **(Canceled)**

13. **(Canceled)**

14. **(Previously Presented)** A method according to claim 10, wherein step (b) includes contacting said surface with an electrically conductive wafer-cleaning brush roller having a non-filamentous cleaning surface.

15. **(Canceled)**

16. **(Canceled)**

17. **(Previously Presented)** A system for removing surface contaminants from a surface, comprising:

- (a) a microelectronics wafer having a surface;
- (b) an electrical ground;
- (c) a wafer-cleaning region receiving said microelectronics wafer; and
- (d) a conductive rotating wafer-cleaning member operatively configured to engage said surface of microelectronics wafer in said wafer cleaning region so as to remove contaminants from said surface and provide part of a grounding path between said microelectronics wafer and said electrical ground for removing electrical charge from said microelectronics wafer.

18. **(Previously Presented)** A system according to claim 17, wherein said rotating wafer-cleaning member comprises a brush roller having a non-filamentous cleaning surface.

19. **(Canceled)**

20. **(Canceled)**

21. **(Canceled).**